82704 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. Patent Application)
Applicant:	Karl-Heinz SCHUSTER))
Serial No.:	Not Yet Assigned)
Filed:	Herewith)
For:	PROJECTION LENS, IN PARTICULAR FOR MICROLITHOGRAPHY)))

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

This is a Preliminary Amendment for entry in the above-identified application.

In the Specification:

Please replace the enclosed specification with the enclosed Substitute Specification.

Applicant avers that no new matter has been added.

In the Claims:

Please amend the claims as follows:

- 4. (amended) Projection lens according to claim 1, wherein the manipulation chamber is located between the lens arrangement and the image plane.
- 5. (amended) Projection lens according to claim 1, wherein the manipulation chamber is located in the lens arrangement.

11. (amended) Projection lens according to claim 8, wherein the first optical element and a second optical element of the sixth optical group enclose a gas chamber, wherein it holds for the radius of curvature R3 of the surface of the second optical element, which faces the first lens, that:

|R3| > 3000 mm.

- 12. (amended) Projection lens according to claim 11, wherein it holds for the radius of curvature R3 that: |R3| > 5000 mm.
- (amended) Projection lens according to claim 11, wherein it holds for the radius of curvature R4 of the further surface of the second optical element that:
 |R4| > 3000 mm, preferably |R4| > 5000 mm.
- 15. (amended) Projection lens according to claim 8, wherein a lens with an aspheric surface is provided in the first lens cluster.
- 17. (amended) Projection lens according to claim 15, wherein the aspheric surface is arranged on the first curved surface of the aspheric lens.
- 25. (amended) System for projection lens according to claim 19, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on a substrate, which is to be exposed, in the sixth optical group.
- 26. (amended) System for projection lens according to claim 20, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on a substrate, which is to be exposed, in a sixth optical group.

- 27. (amended) System for projection lens according to claim 21, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on a substrate, which is to be exposed, in a sixth optical group.
- 34. (amended) Method according to claim 29, wherein when the projection lens is being tuned a filling gas is introduced which is subsequently exchanged by the operator for a gas mixture.
- 36. (amended) Method for producing microstructured components, in the case of which a substrate provided with a light-sensitive layer is exposed by ultraviolet light by means of a mask and a projection exposure machine according to claim 26 and is structured after the development of the light-sensitive layer in accordance with a pattern included on the mask.

Respectfully submitted,

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By

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

- 4. (amended) Projection lens according to claim 1[, 2 or 3], wherein the manipulation chamber is located between the lens arrangement and the image plane.
- 5. (amended) Projection lens according to claim 1[, 2 or 3], wherein the manipulation chamber is located in the lens arrangement.
- 11. (amended) Projection lens according to claim 8[, 9 or 10], wherein the first optical element and a second optical element of the sixth optical group enclose a gas chamber, wherein it holds for the radius of curvature R3 of the surface of the second optical element, which faces the first lens, that:

 |R3| > 3000 mm.
- 12. (amended) Projection lens according to claim 11[or 12], wherein it holds for the radius of curvature R3 that: |R3| > 5000 mm.
- 13. (amended) Projection lens according to claim 11[or 12], wherein it holds for the radius of curvature R4 of the further surface of the second optical element that:

 |R4| > 3000 mm, preferably |R4| > 5000 mm.
- 15. (amended) Projection lens according to [one of the] claim[s] <u>8</u> [1 to , wherein a lens] with an aspheric surface is provided in the first lens cluster [(LG1)].
- 17. (amended) Projection lens according to claim 15 [or 16], wherein the aspheric surface is arranged on the first curved surface of the aspheric lens.

- 25. (amended) System for projection lens according to claim 19, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on a substrate, which is to be exposed, in the sixth optical group [(LG6)].
- 26. (amended) System for projection lens according to claim 20, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on <u>a</u> [the] substrate, which is to be exposed, in a sixth optical group [(LG6)].
- 27. (amended) System for projection lens according to claim 21, wherein in addition to the manipulation chamber a further at least approximately plane-parallel manipulable gas interspace is provided, for the purpose of removing field curvature, on <u>a</u> [the] substrate, which is to be exposed, in a sixth optical group [(LG6)].
- 34. (amended) Method according to claim[s] 29 [and 33], wherein when the projection lens is being tuned a filling gas is introduced which is subsequently exchanged by the operator for a gas mixture.
- 36. (amended) Method for producing microstructured components, in the case of which a substrate provided with a light-sensitive layer is exposed by ultraviolet light by means of a mask and a projection exposure machine according to claim 26 and[, if appropriate,] is structured after the development of the light-sensitive layer in accordance with a pattern included on the mask.